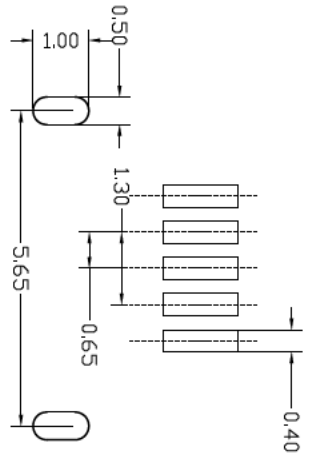
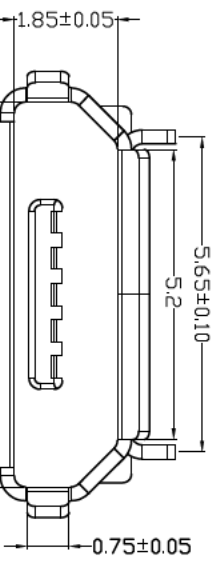
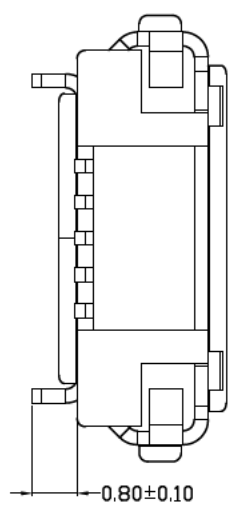
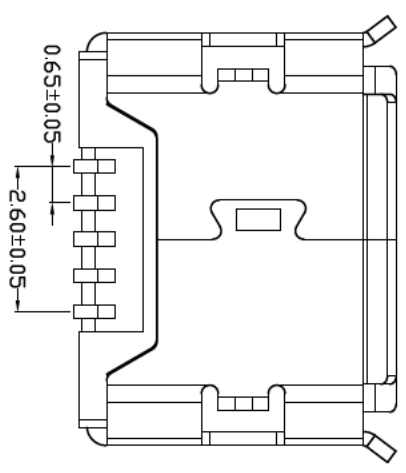
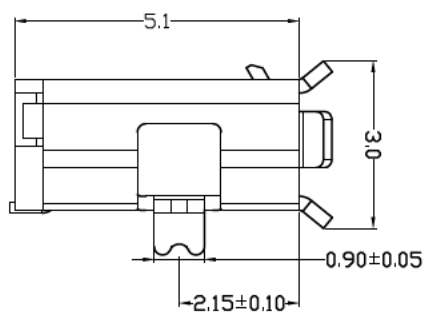
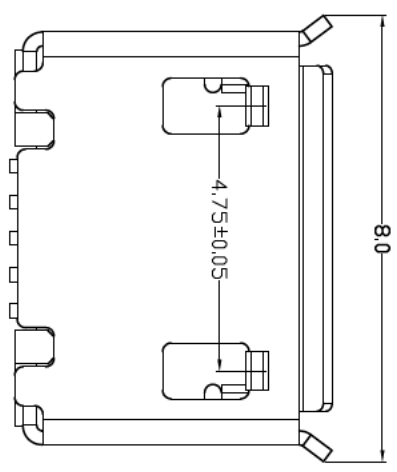


| REVISION RECORD | | | | |
|-----------------|-----|-------------|------|------|
| REV | ECO | DESCRIPTION | DRFT | CHKD |
| | | | | |



PCB LAYOUT



- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f.Ul94v-0
 - Contact: copper alloy, t=0.20mm
 - Shell: SUS, t=0.25mm
 - Specification:
 - Current rating: 1A Max
 - Dielectric withstanding voltage: 100V (AC) for 1 min.
 - Contact resistance: 50mΩ Max.
 - Insulation resistance: 100mΩ min.
 - Total mating force: 3.57 KgF Max.
 - Total unmating force: 1.0 KgF Min. 0.81~2.05 KgF Min. after 10,000 insertion/extraction cycles
 - Temperature range: -30° C~80° C

| DETACHED LISTS | | DATE: 2007/5/13 | |
|---------------------------|----------|---------------------|-----------------|
| TOLERANCE EXCEPT AS NOTED | UNIT: MM | DRFT: SIB | DATE: 2007/5/13 |
| MM | MM | CHGD: LINDO | DATE: 2007/5/13 |
| A ± 0.15 | 1 | APPR: / | DATE: / |
| MM ± 0.15 | 1 | MATERIAL: / | DATE: / |
| ANGLES ± 0.5 | 1 | QTY: / | DATE: / |
| THIRD ANGLE PROJECTION | SCALE: / | FINISH: / | DATE: / |
| TITLE | | DRAWING NO. T59A009 | |
| Micro USB 5P BF DIP 5.65 | | PART NO. / | |
| SM C04 8368 05BF | | SIZE REV | |
| DO NOT SCALE DRAWING | | A3 0 | |
| SHEET X | | OF Y | |

8 7 6 5 4 3 2 1